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(12) **United States Design Patent**
Chung

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(54) **HEAT SINK FOR MEMORY MODULES**

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(73) Assignee: **ESSENCORE Limited**, Hong Kong (HK)

(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179; D14/435
CPC H01L 23/28; H01L 23/36; H01L 23/367; H01L 23/3672; H01L 23/3675; H01L 23/3677; H01L 23/4093; H01L 23/467; G06F 1/20; H05K 7/2039; H05K 7/20509
See application file for complete search history.

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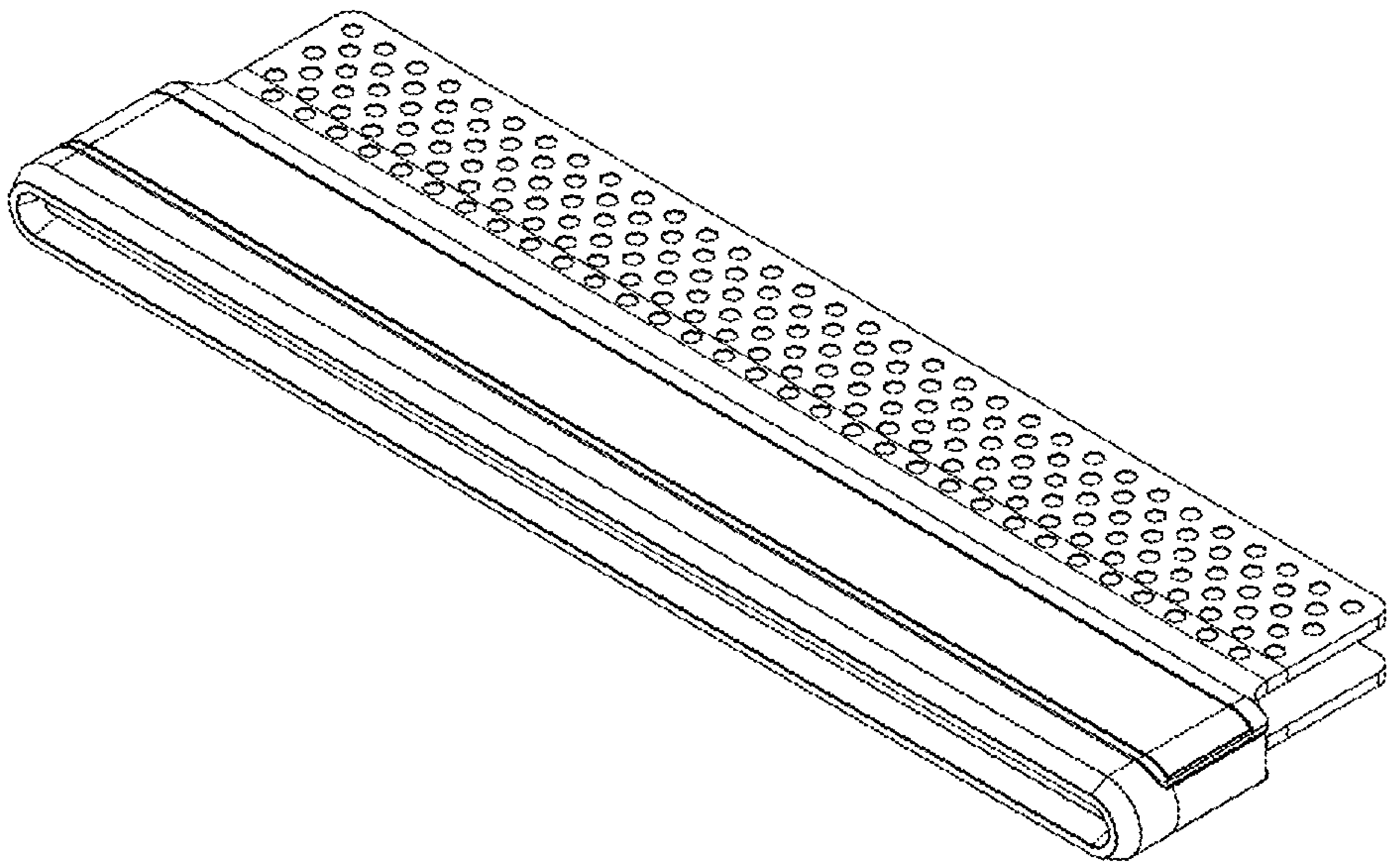
(57) **CLAIM**

The ornamental design for a heat sink for memory modules, as shown and described.

DESCRIPTION

FIG. **1** is a top, front perspective view of the heat sink for memory modules;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a top view thereof; and,
FIG. **7** is a bottom view thereof.

1 Claim, 5 Drawing Sheets



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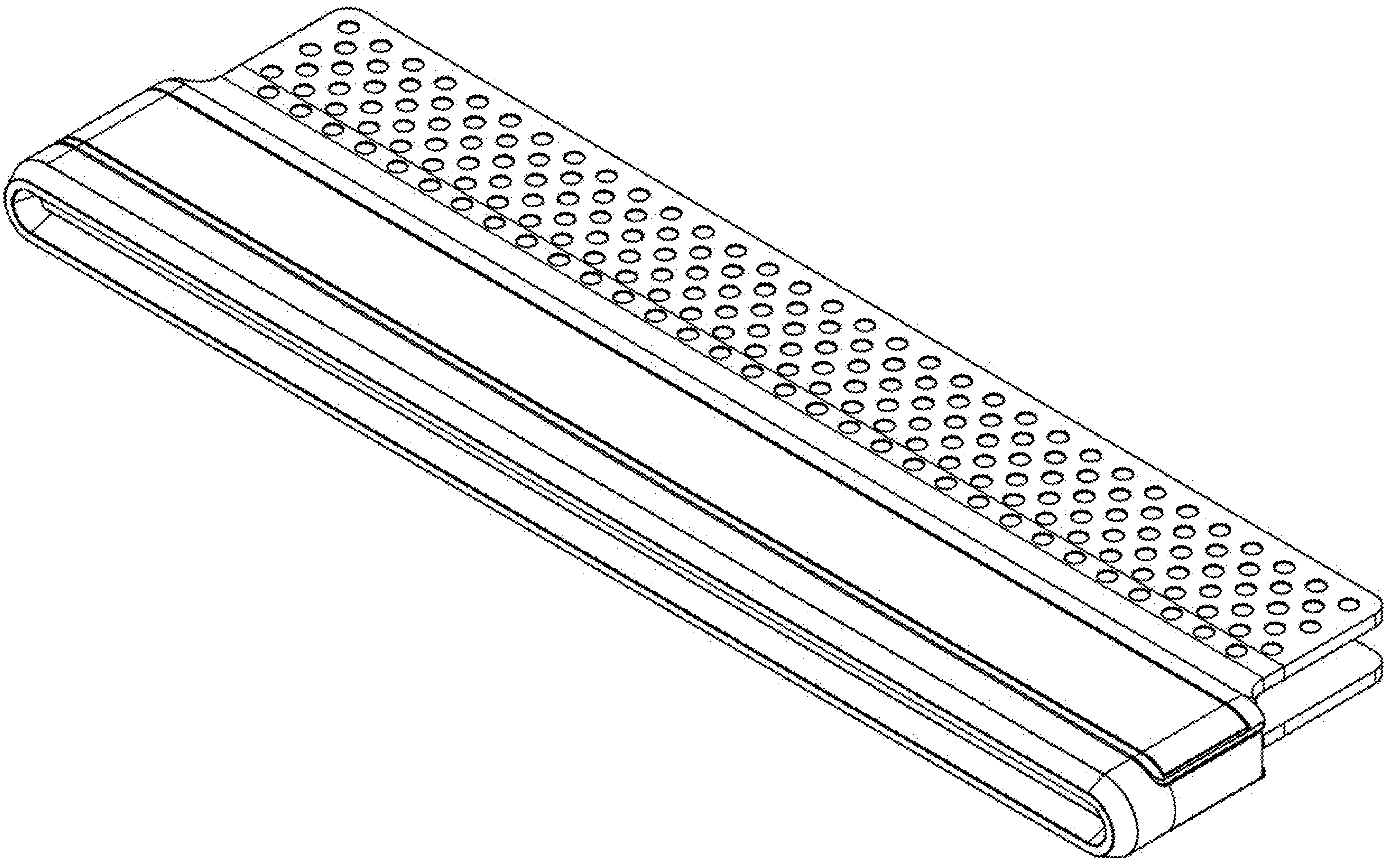

FIG. 1

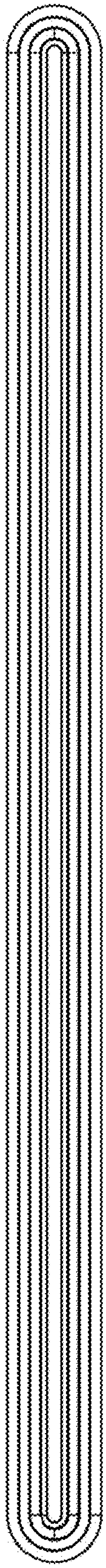

FIG. 2

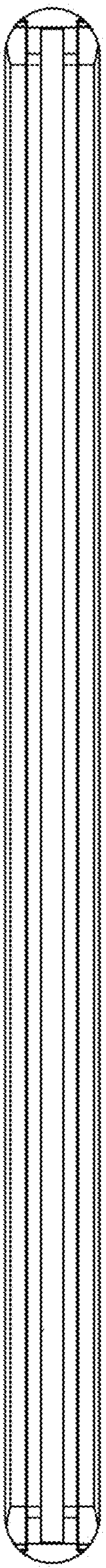

FIG. 3

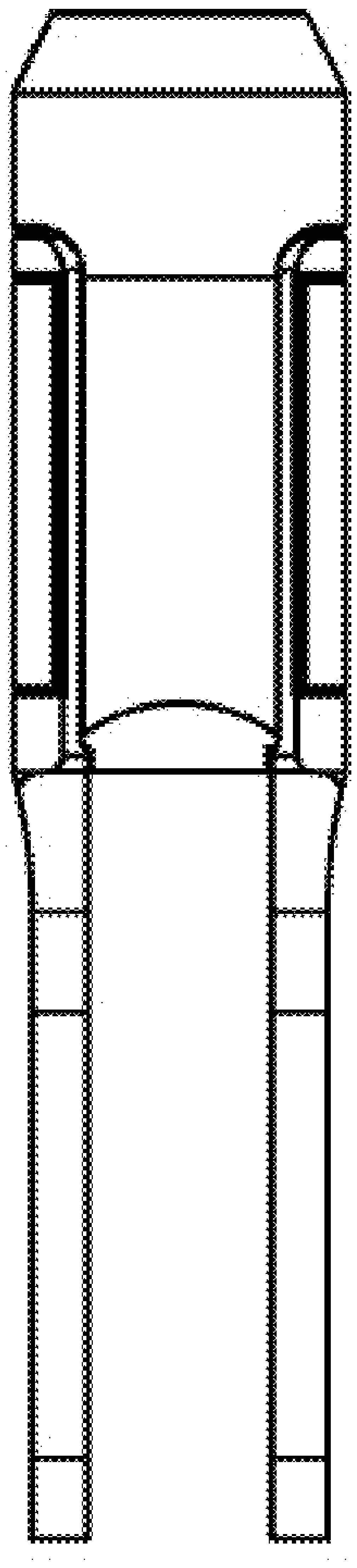

FIG. 4

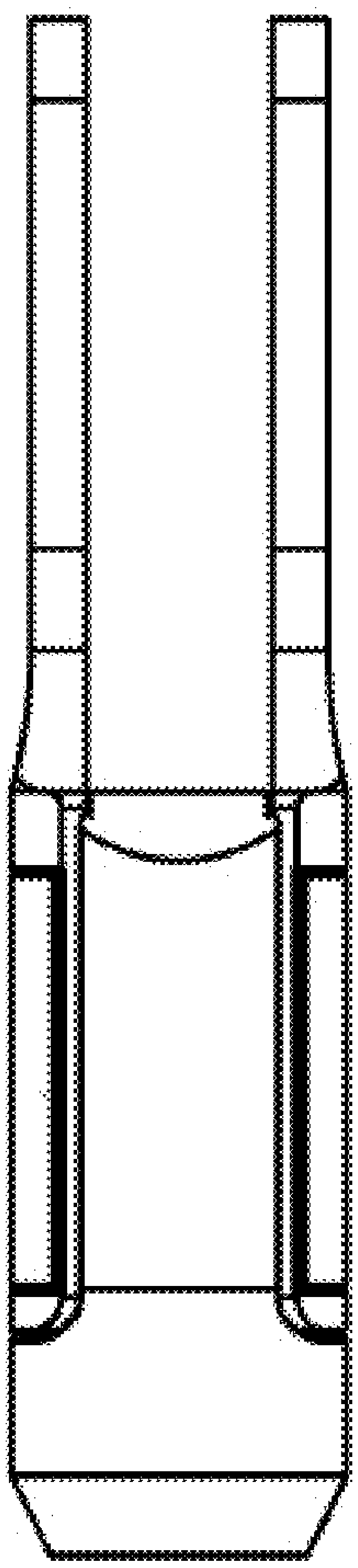

FIG. 5

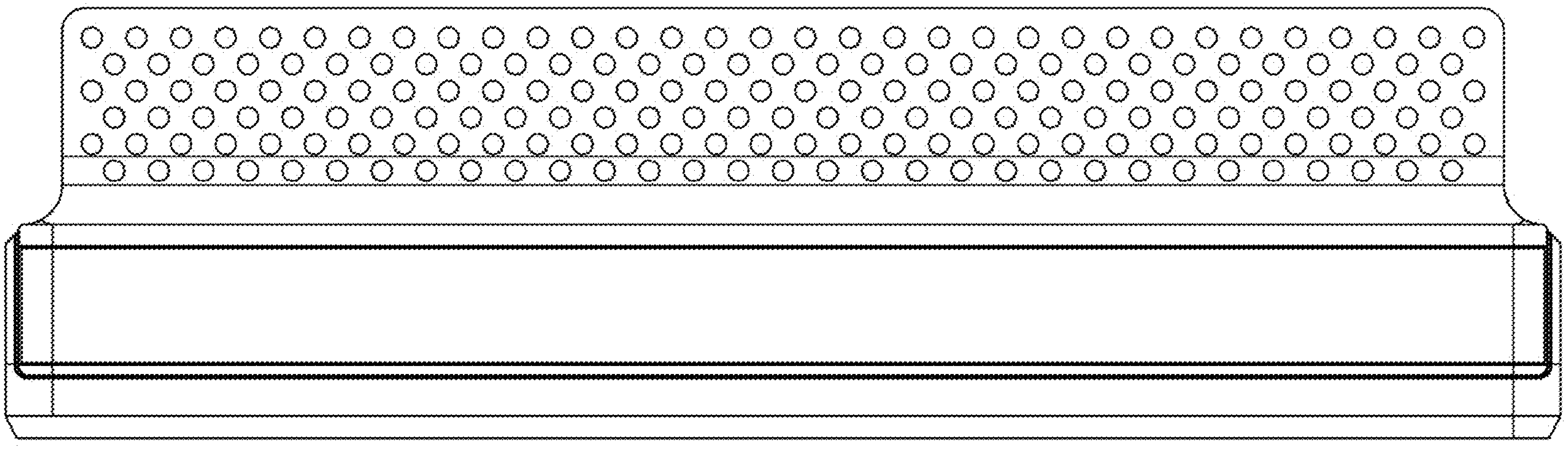

FIG. 6

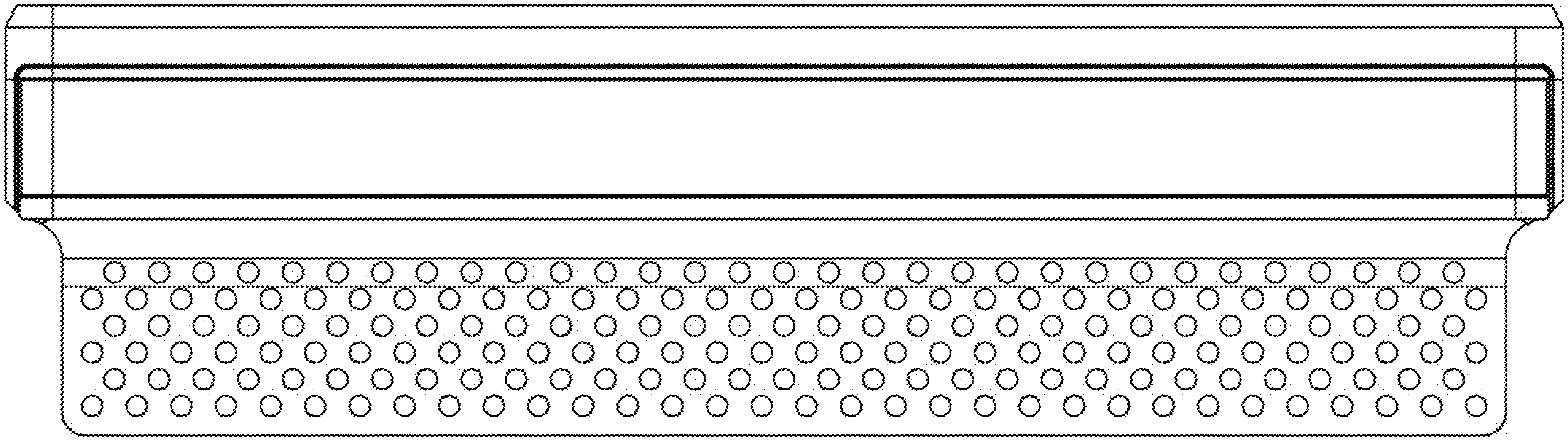

FIG. 7